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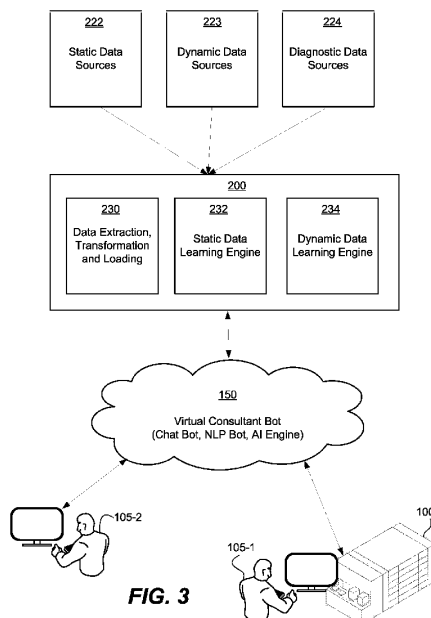
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(54) Title: AUTOMATED ASSISTANCE IN A SEMICONDUCTOR MANUFACTURING ENVIRONMENT



(57) Abstract: In one embodiment, a system includes a wafer-handling system of a semiconductor-manufacturing system. The wafer-handling system is configured to hold one or more wafers for processing. The system also includes one or more processing components configured to physically treat the one or more wafers; a controller configured to operate the processing components; and a text bot in communication with the semiconductor-manufacturing system and configured to respond to a user inquiry.

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